

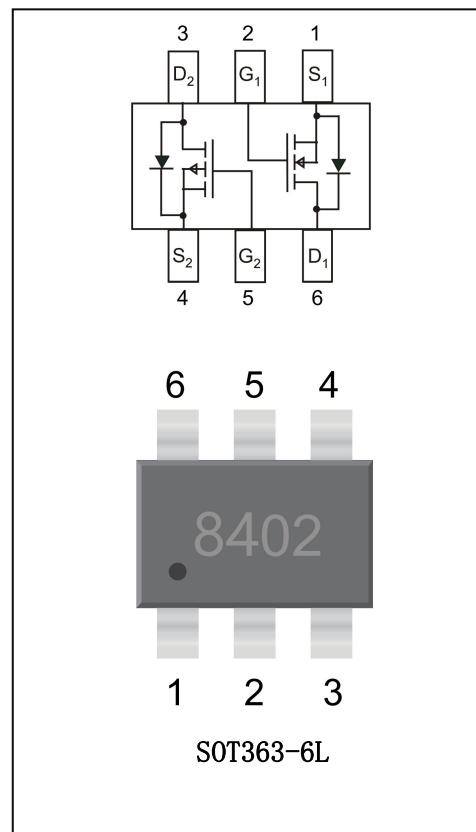
N AND P-CHANNEL POWER MOSFET

GENERAL DESCRIPTION

The SFH8402DW uses advanced trench technology and design to provide excellent $R_{DS(ON)}$ with low gate charge. It can be used in a wide variety of applications.

FEATURES

- ◆ N-CHANNEL
 - $V_{DS}=50V, I_D=0.13A$
 - $R_{DS(ON)}=1.0\Omega$ (TYP@ $V_{GS}=10V$)
 - $R_{DS(ON)}=1.2\Omega$ (TYP@ $V_{GS}=4.5V$)
- ◆ P-CHANNEL
 - $V_{DS}=-50V, I_D=-0.13A$
 - $R_{DS(ON)}=1.6\Omega$ (TYP@ $V_{GS}=-10V$)
 - $R_{DS(ON)}=1.8\Omega$ (TYP@ $V_{GS}=-4.5V$)
- ◆ S-prefix for automotive and other applications requiring unique site and control change requirements;
AEC-Q101 qualified and PPAP capable



ORDERING INFORMATION

Part No.	Package	Marking	Material	Packing
SFH8402DW	SOT363-6L	8402	Pb Free	Reel

ABSOLUTE MAXIMUM RATINGS ($T_J=25^\circ\text{C}$ unless otherwise noted)

Characteristics		Symbol	N-CHANNEL	P-CHANNEL	UNIT
Drain-Source Voltage		V_{DS}	50	-50	V
Gate-Source Voltage		V_{GS}	± 20	± 20	
Drain Current	TC=25°C	I_D	0.13	-0.13	A
	TC=70°C		0.09	-0.09	
Pulsed Drain Current(note1)		I_{DM}	0.52	-0.52	
Power Dissipation	TC=25°C	P_D	0.4		W
Thermal Characteristics					
Maximum Junction-to-Lead		$R_{\theta JL}$	312.5		°C/W
Junction and Storage Temperature Range		T_J, T_{stg}	-55 to +150		°C
Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds		T_L	300		

N-CHANNEL ELECTRICAL CHARACTERISTICS

Characteristics	Symbol	Test conditions	Min.	Typ.	Max.	Unit
Off Characteristics						
Drain -Source Breakdown Voltage	B_{VDSS}	$V_{GS}=0V, I_D=250\mu\text{A}$	50	--	-	V
Drain-Source Leakage Current	I_{DSS}	$V_{DS}=50\text{V}, V_{GS}=0\text{V}$	-	--	1.0	μA
Gate-Source Leakage Current	I_{GSS}	$V_{GS}=20\text{V}, V_{DS}=0\text{V}$	-	--	100	nA
Gate-Source Leakage Current	I_{GSS}	$V_{GS}=-20\text{V}, V_{DS}=0\text{V}$	-	--	-100	
On Characteristics						
Gate Threshold Voltage	$V_{GS(th)}$	$V_{GS}=V_{DS}, I_D=250\mu\text{A}$	0.5	1.2	1.5	V
Static Drain- Source On State Resistance	$R_{DS(on)}$	$V_{GS}=10\text{V}, I_D=0.2\text{A}$	-	1.0	1.5	Ω
		$V_{GS}=5.0\text{V}, I_D=0.2\text{A}$	-	1.2	1.7	
Dynamic Characteristics						
Input Capacitance	C_{iss}	$V_{DS}=25\text{V}$	-	42	-	pF
Output Capacitance	C_{oss}		-	15	-	
Reverse Transfer Capacitance	C_{rss}		f=1.0MHZ	3	-	
Switching Characteristics						
Turn-on Delay Time	$t_{d(on)}$	$V_{DD}=25\text{V}, V_{GS}=10\text{V}$ $R_G=160\Omega, I_D=0.2\text{A}$ (Note 2.3)	-	17.8	-	ns
Turn-on Rise Time	t_r		-	5.3	-	
Turn-off Delay Time	$t_{d(off)}$		-	21.5	-	
Turn-off Fall Time	t_f		-	3.6	-	

N-CHANNEL SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS

Characteristics	Symbol	Test conditions	Min.	Typ.	Max.	Unit
Continuous Source Current	I_S	Integral Reverse P-N Junction Diode in the MOSFET	-	-	0.13	A
Pulsed Source Current	I_{SM}		-	-	0.52	
Diode Forward Voltage	V_{SD}	$I_S=0.2\text{A}, V_{GS}=0\text{V}$	-	0.8	1.2	V

P-CHANNEL ELECTRICAL CHARACTERISTICS

Characteristics	Symbol	Test conditions	Min.	Typ.	Max.	Unit
Off Characteristics						
Drain -Source Breakdown Voltage	V_{DSS}	$V_{GS}=0V, I_D=-250\mu A$	-50	-	-	V
Drain-Source Leakage Current	I_{DS}	$V_{DS}=-50V, V_{GS}=0V$	-	-	-1.0	μA
Gate-Source Leakage Current	I_{GSS}	$V_{GS}=20V, V_{DS}=0V$	-	-	100	nA
Gate-Source Leakage Current	I_{GSS}	$V_{GS}=-20V, V_{DS}=0V$	-	-	-100	
On Characteristics						
Gate Threshold Voltage	$V_{GS(th)}$	$V_{GS}=V_{DS}, I_D=-250\mu A$	-1.0	-1.45	-2.0	V
Static Drain- Source On State Resistance	$R_{DS(on)}$	$V_{GS}=-10V, I_D=-0.1A$	-	1.6	2.5	Ω
		$V_{GS}=-5.0V, I_D=-0.1A$	-	1.8	3.0	
Dynamic Characteristics						
Input Capacitance	C_{iss}	$V_{DS}=-25V$ $V_{GS}=0V$ $f=1.0MHz$	-	30	-	pF
Output Capacitance	C_{oss}		-	10	-	
Reverse Transfer Capacitance	C_{rss}		-	5.0	-	
Switching Characteristics						
Turn-on Delay Time	$t_{d(on)}$	$V_{DD}=-25V$ $V_{GS}=-10V$ $R_G=160\Omega$ $I_D=-0.1A$ <small>(Note 2.3)</small>	-	16.7	-	ns
Turn-on Rise Time	t_r		-	8.6	-	
Turn-off Delay Time	$t_{d(off)}$		-	17.9	-	
Turn-off Fall Time	t_f		-	5.3	-	

P-CHANNEL SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS

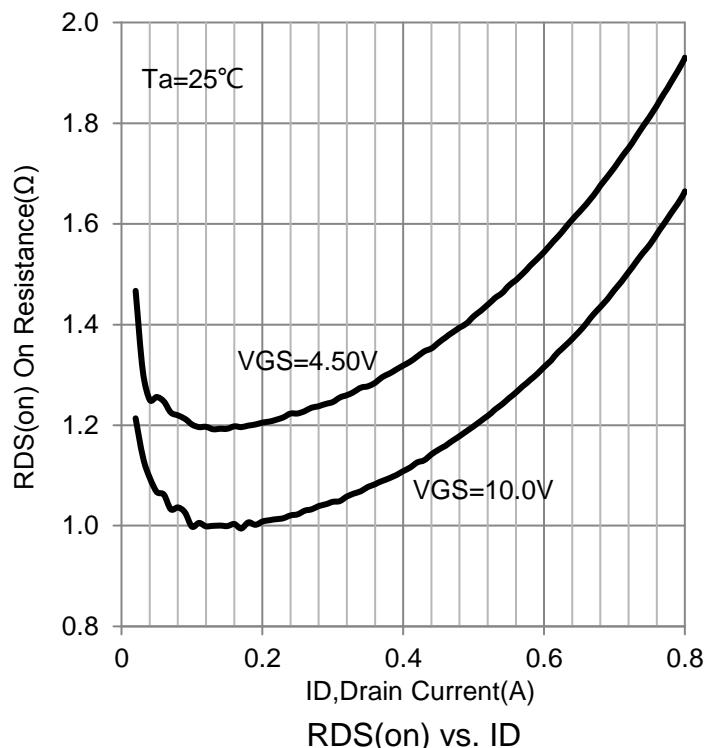
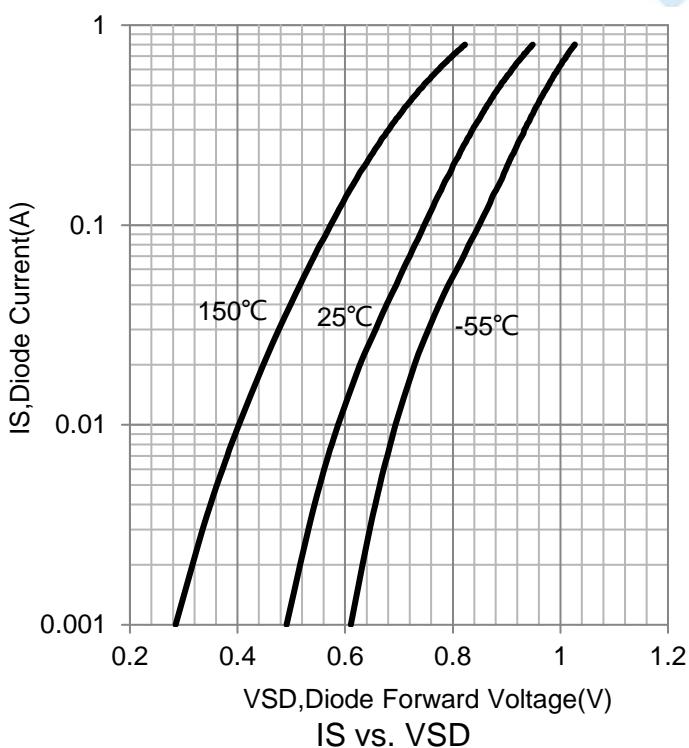
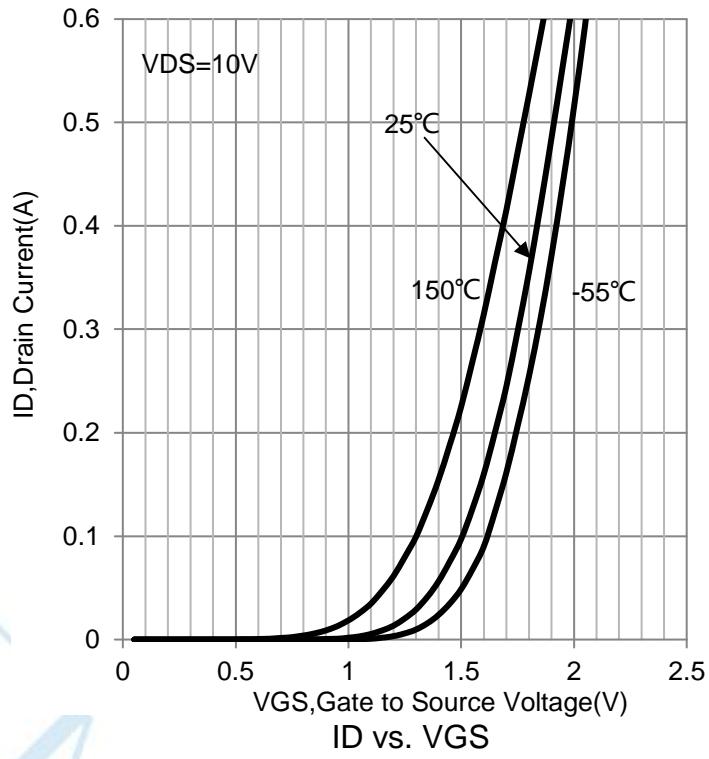
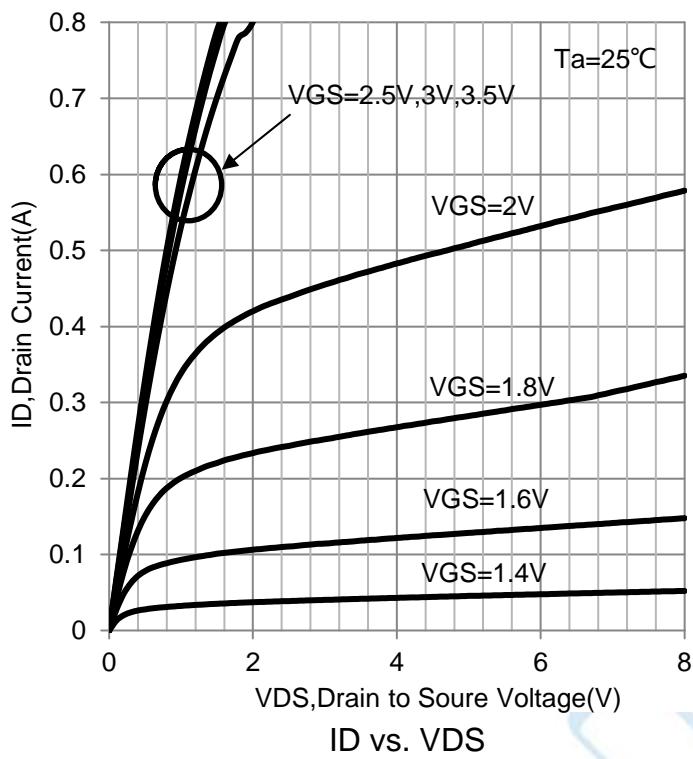
Characteristics	Symbol	Test conditions	Min.	Typ.	Max.	Unit
Continuous Source Current	I_s	Integral Reverse P-N Junction Diode in the MOSFET	-	-	-0.13	A
Pulsed Source Current	I_{SM}		-	-	-0.52	
Diode Forward Voltage	V_{SD}		$I_s=-0.2A, V_{GS}=0V$	-	-0.8	-1.2

1.Pulse width limited by maximum junction temperature

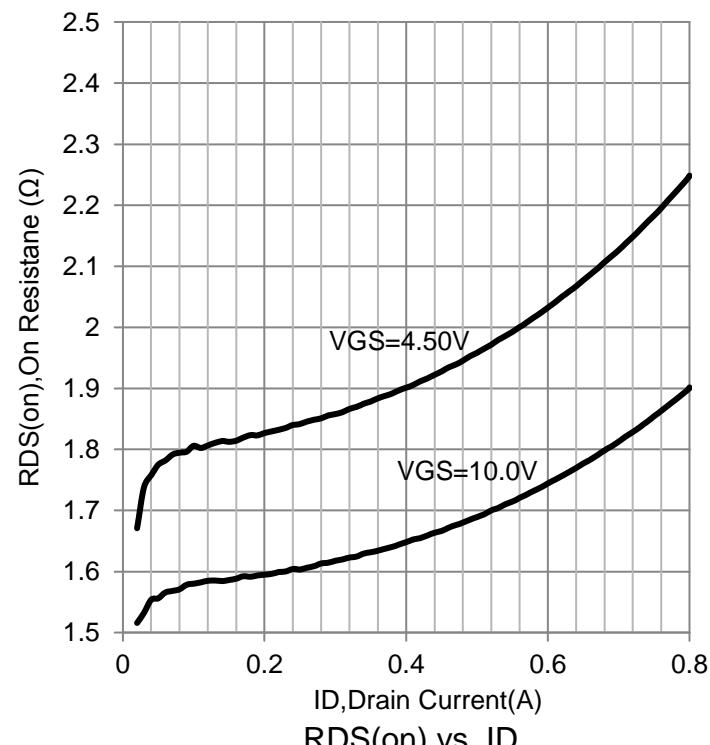
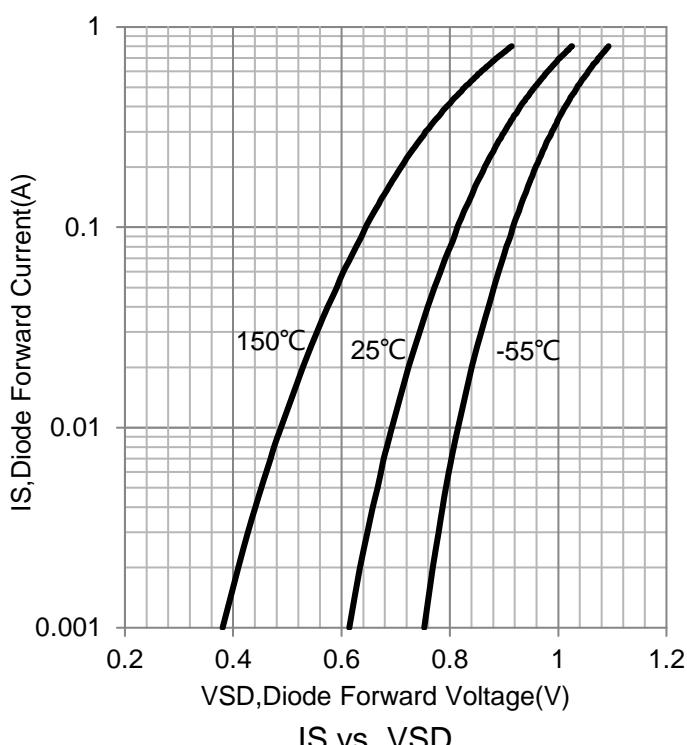
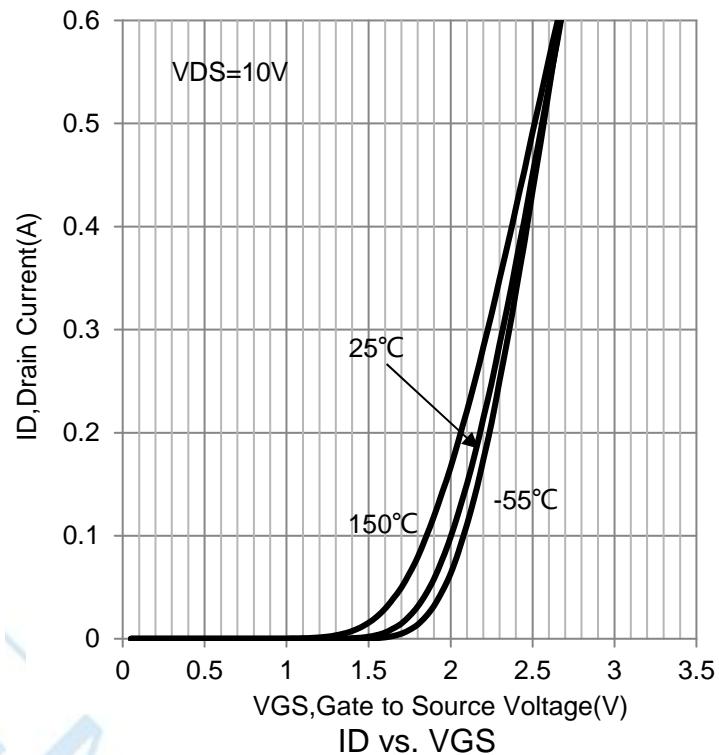
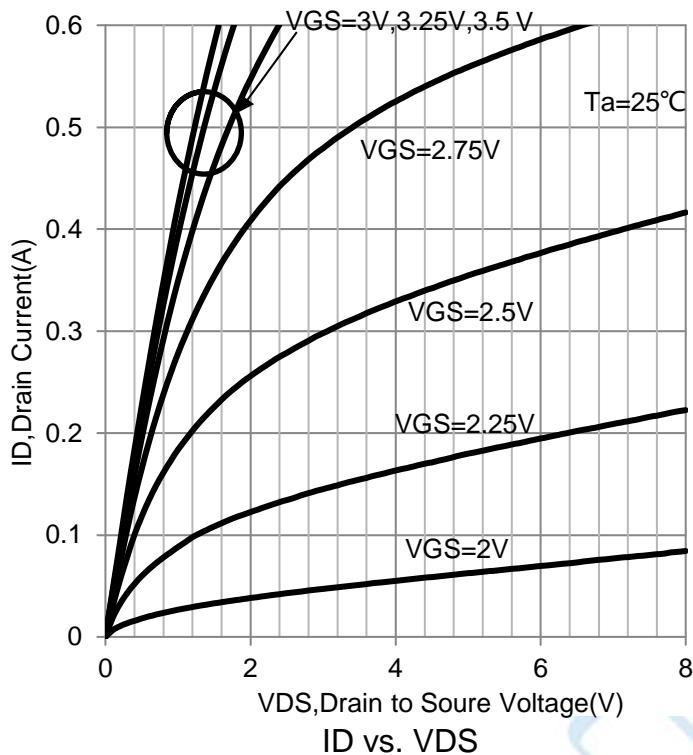
2.Pulse Test: Pulse width $\leq 300\mu s$, Duty cycle $\leq 2\%$

3.Essentially independent of operating temperature

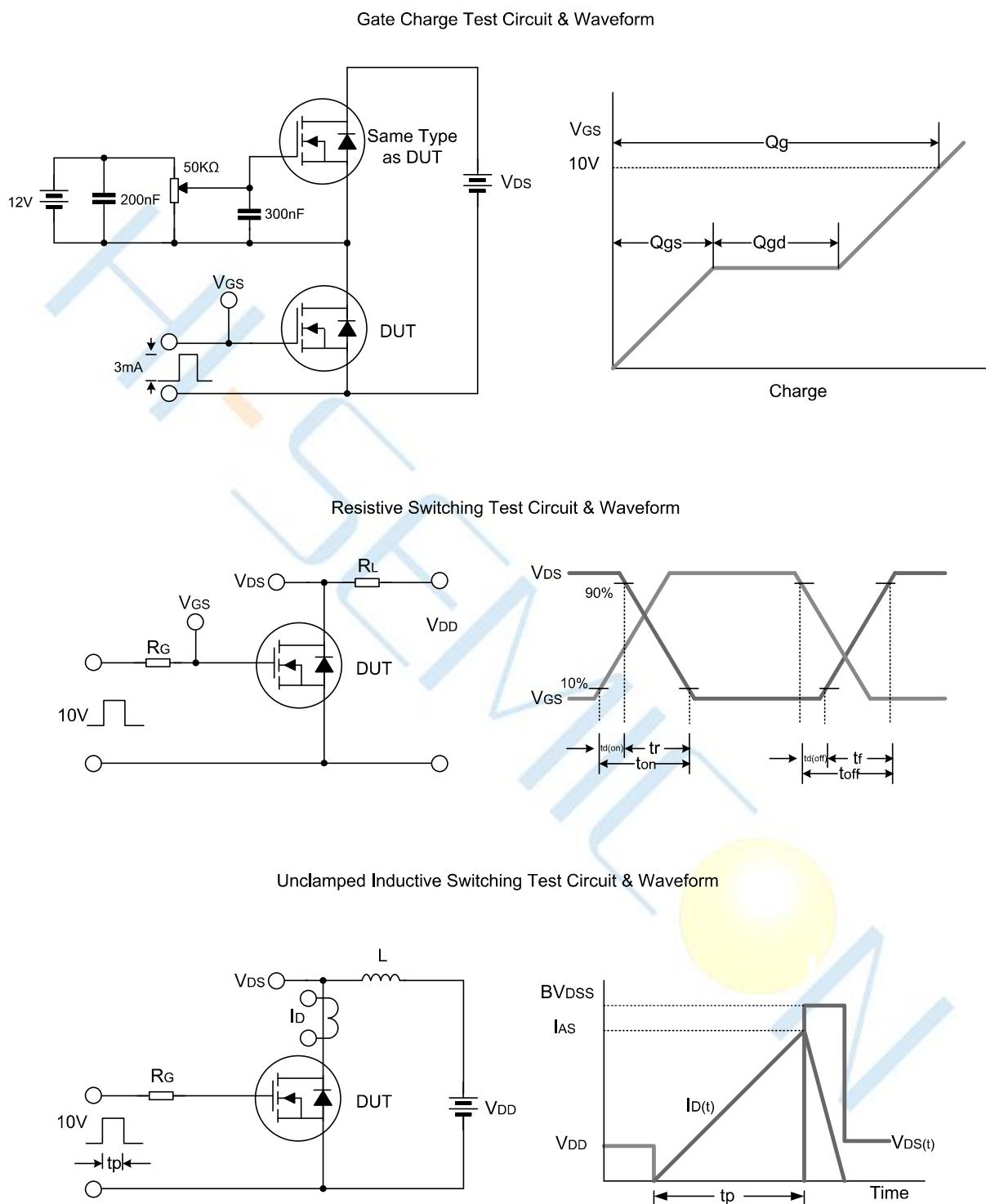
N-CHANNEL Typical Performance Characteristics



P-CHANNEL Typical Performance Characteristics

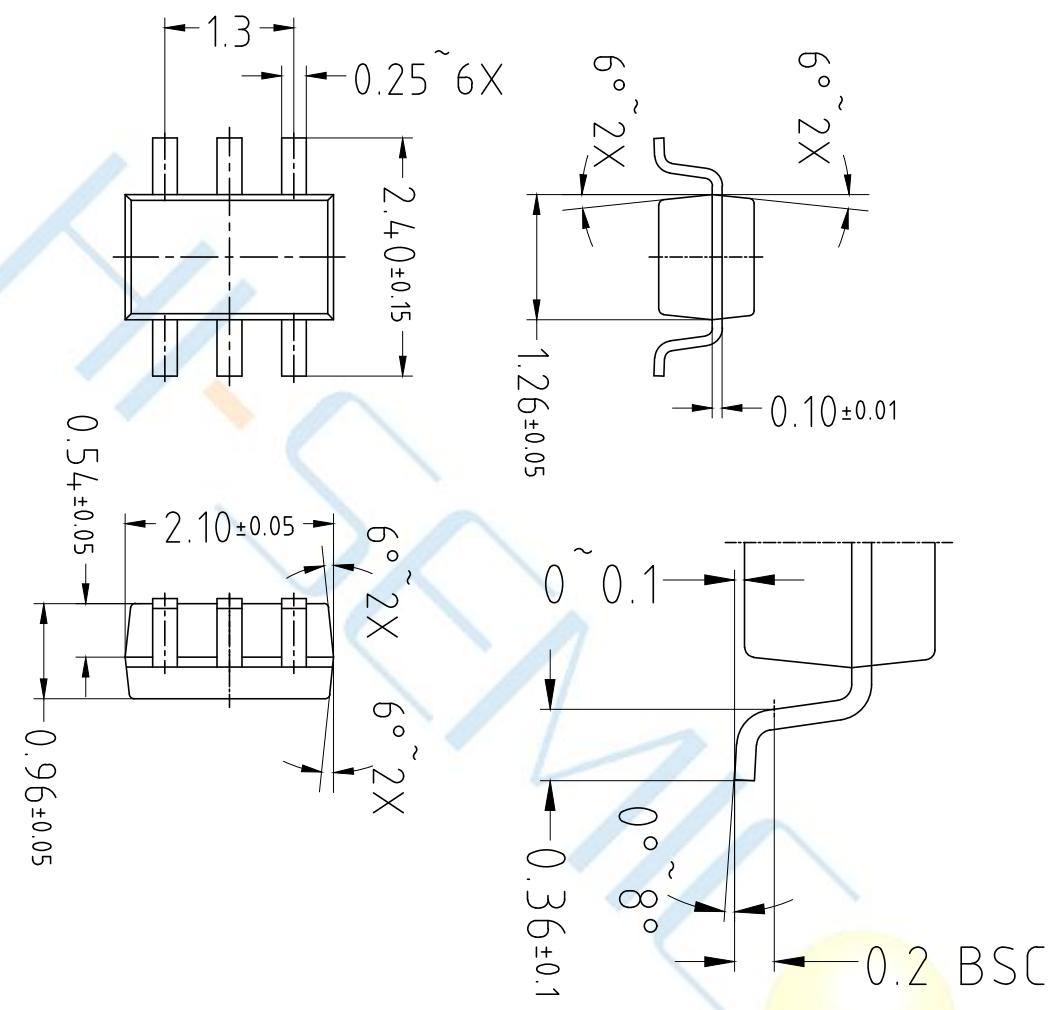


Test Circuit



Package Dimensions of SOT363-6L

Unit:mm



Disclaimer:

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